

General Description

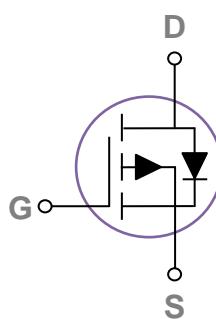
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDS(ON)	ID
-100V	95mΩ	-24A

Features

- -100V,-24A, RDS(ON) 95mΩ@VGS = -10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

TO220 Pin Configuration



Applications

- Networking
- Load Switch
- LED applications

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	-24	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	-15.1	A
I_{DM}	Drain Current – Pulsed ¹	-96	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	125	W
	Power Dissipation – Derate above 25°C	1	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.0	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$, $I_D=-1\text{mA}$	---	0.06	---	V/C
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-100\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	μA
		$V_{DS}=-80\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^{\circ}\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-6\text{A}$	---	75	95	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-3\text{A}$	---	80	110	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu\text{A}$	-1.2	-1.6	-2.2	V
			---	-4.46	---	mV/C

Dynamic and switching Characteristics

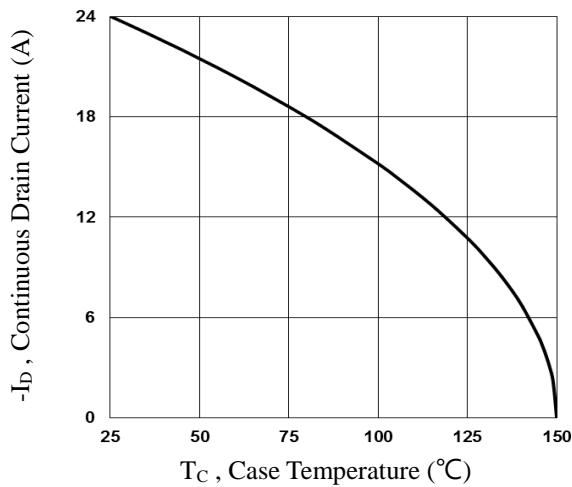
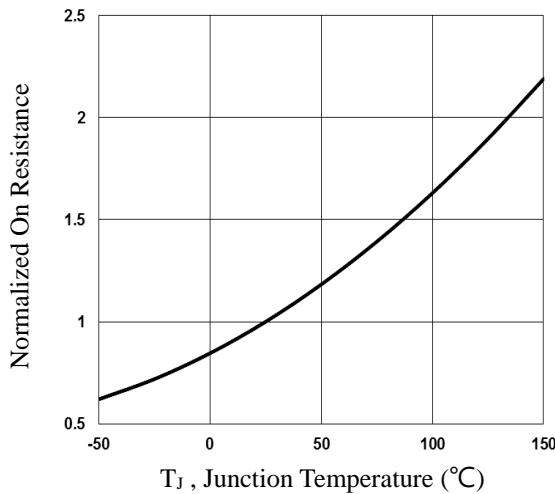
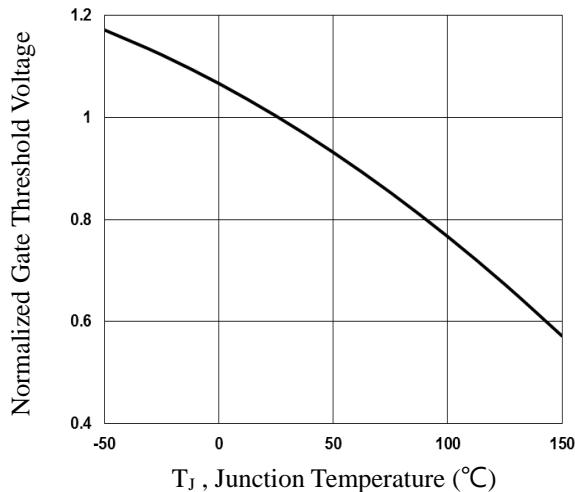
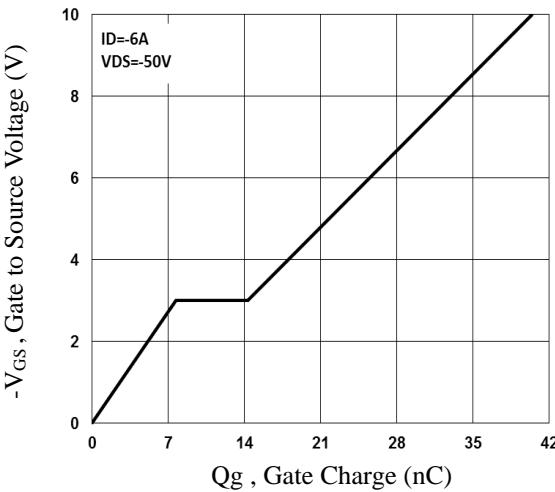
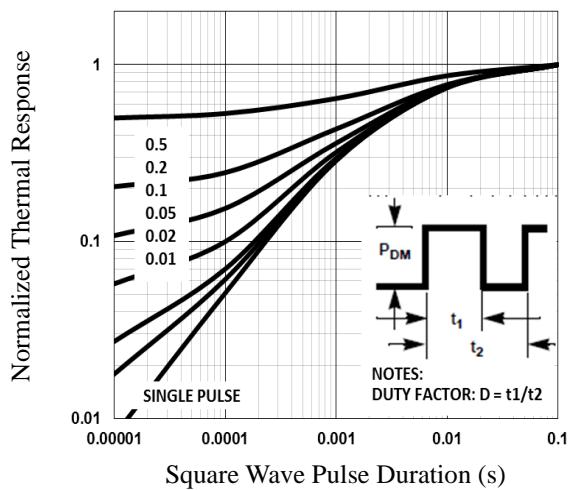
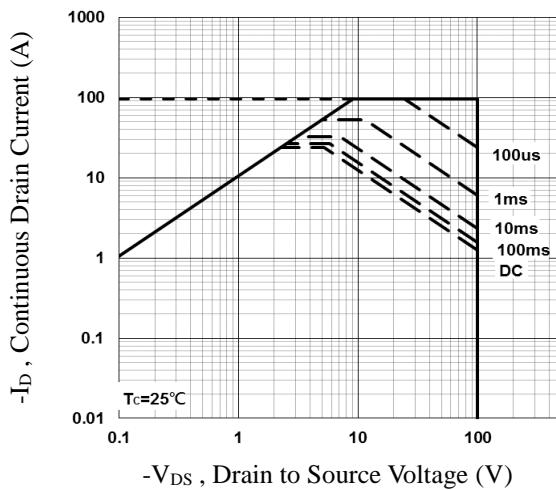
Q_g	Total Gate Charge ^{2, 3}	$V_{DS}=-50\text{V}$, $V_{GS}=-10\text{V}$, $I_D=-6\text{A}$	---	40.4	70	nC
Q_{gs}	Gate-Source Charge ^{2, 3}		---	7.7	15	
Q_{gd}	Gate-Drain Charge ^{2, 3}		---	6.6	13	
$T_{d(on)}$	Turn-On Delay Time ^{2, 3}	$V_{DD}=-30\text{V}$, $V_{GS}=-10\text{V}$, $R_G=6\Omega$ $I_D=-1\text{A}$	---	27	54	ns
T_r	Rise Time ^{2, 3}		---	12	24	
$T_{d(off)}$	Turn-Off Delay Time ^{2, 3}		---	150	300	
T_f	Fall Time ^{2, 3}		---	45	90	
C_{iss}	Input Capacitance	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	2250	3900	pF
C_{oss}	Output Capacitance		---	130	250	
C_{rss}	Reverse Transfer Capacitance		---	90	180	
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $F=1\text{MHz}$	---	10	---	Ω

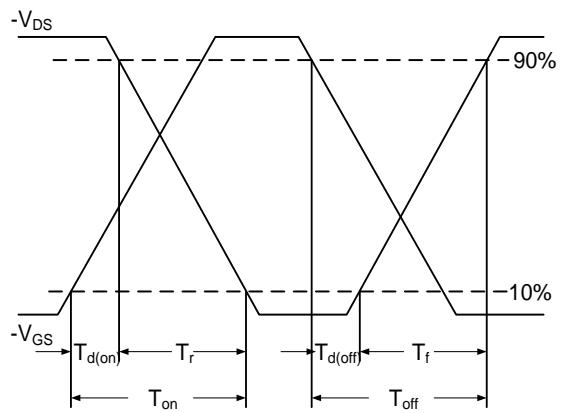
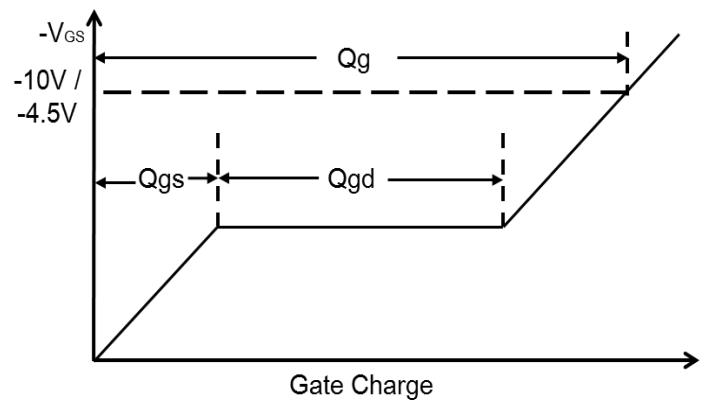
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-24	A
			---	---	-48	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1.2	V
t_{rr}	Reverse Recovery Time	$V_R=-100\text{V}$, $I_s=-10\text{A}$	---	50	---	ns
Q_{rr}	Reverse Recovery Charge	$di/dt=100\text{A}/\mu\text{s}$, $T_J=25\text{ }^{\circ}\text{C}$	---	60	---	nC

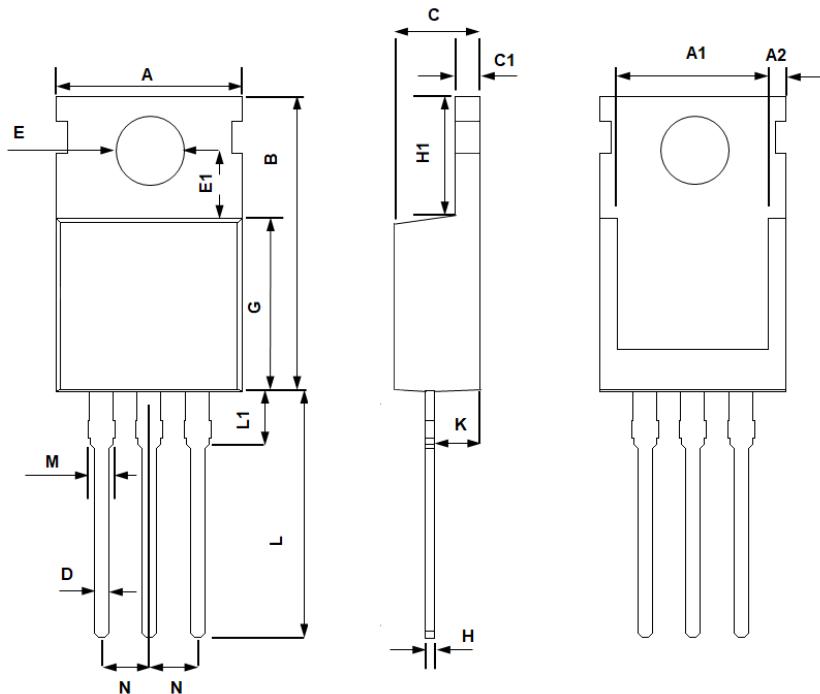
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_C

Fig.2 Normalized R_{DS(on)} vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area


Fig.7 Switching Time Waveform

Fig.8 Gate Charge Waveform

TO220 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.400	9.700	0.409	0.382
A1	8.900	7.400	0.350	0.291
A2	1.400	0.800	0.055	0.031
B	16.500	14.500	0.650	0.571
C	4.750	4.200	0.187	0.165
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	4.000	3.300	0.157	0.130
E1	3.800	3.400	0.150	0.134
G	9.400	8.400	0.370	0.331
H	0.600	0.200	0.024	0.008
H1	6.850	6.200	0.270	0.244
K	2.850	2.100	0.112	0.083
L	14.000	12.500	0.551	0.492
L1	4.000	2.700	0.157	0.106
M	1.750	1.100	0.069	0.043
N	2.640	2.440	0.104	0.096